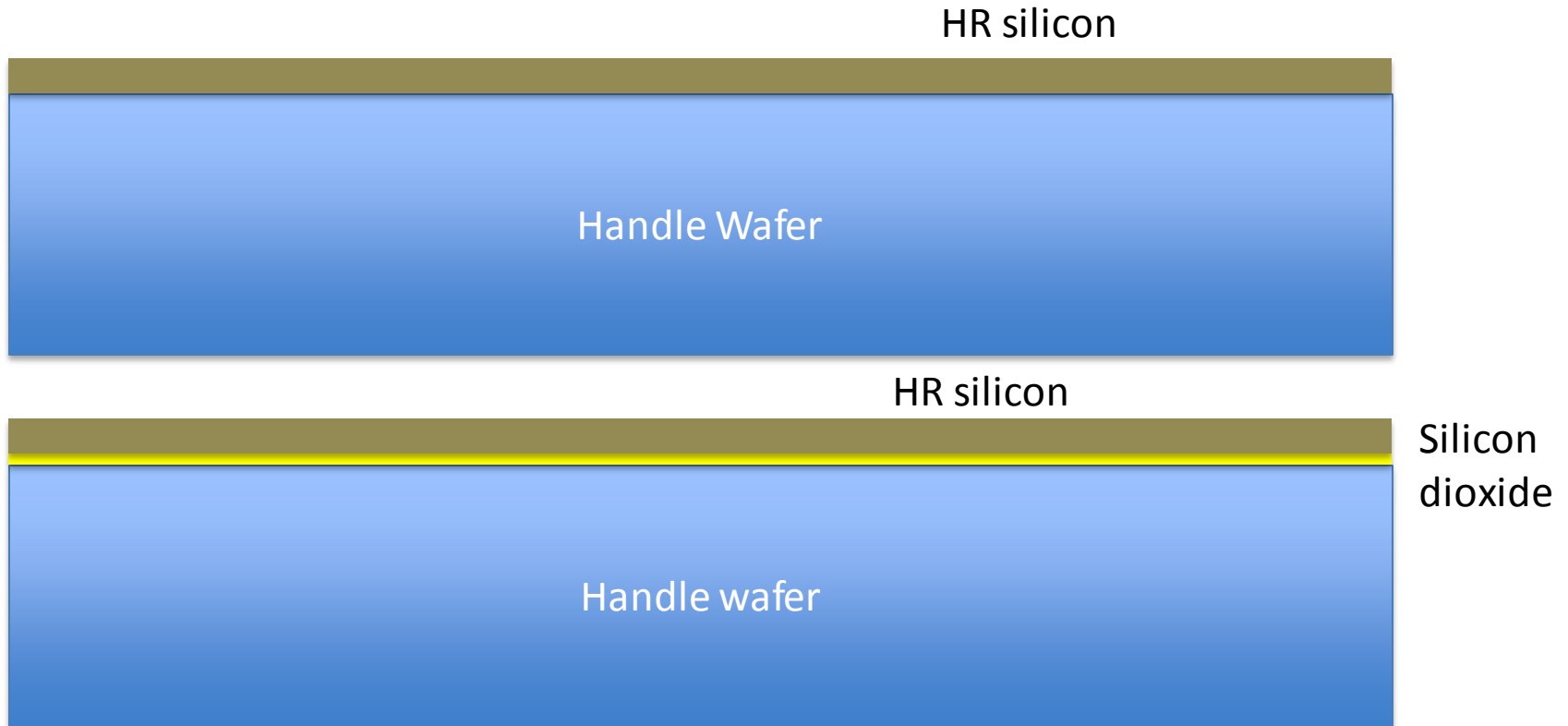


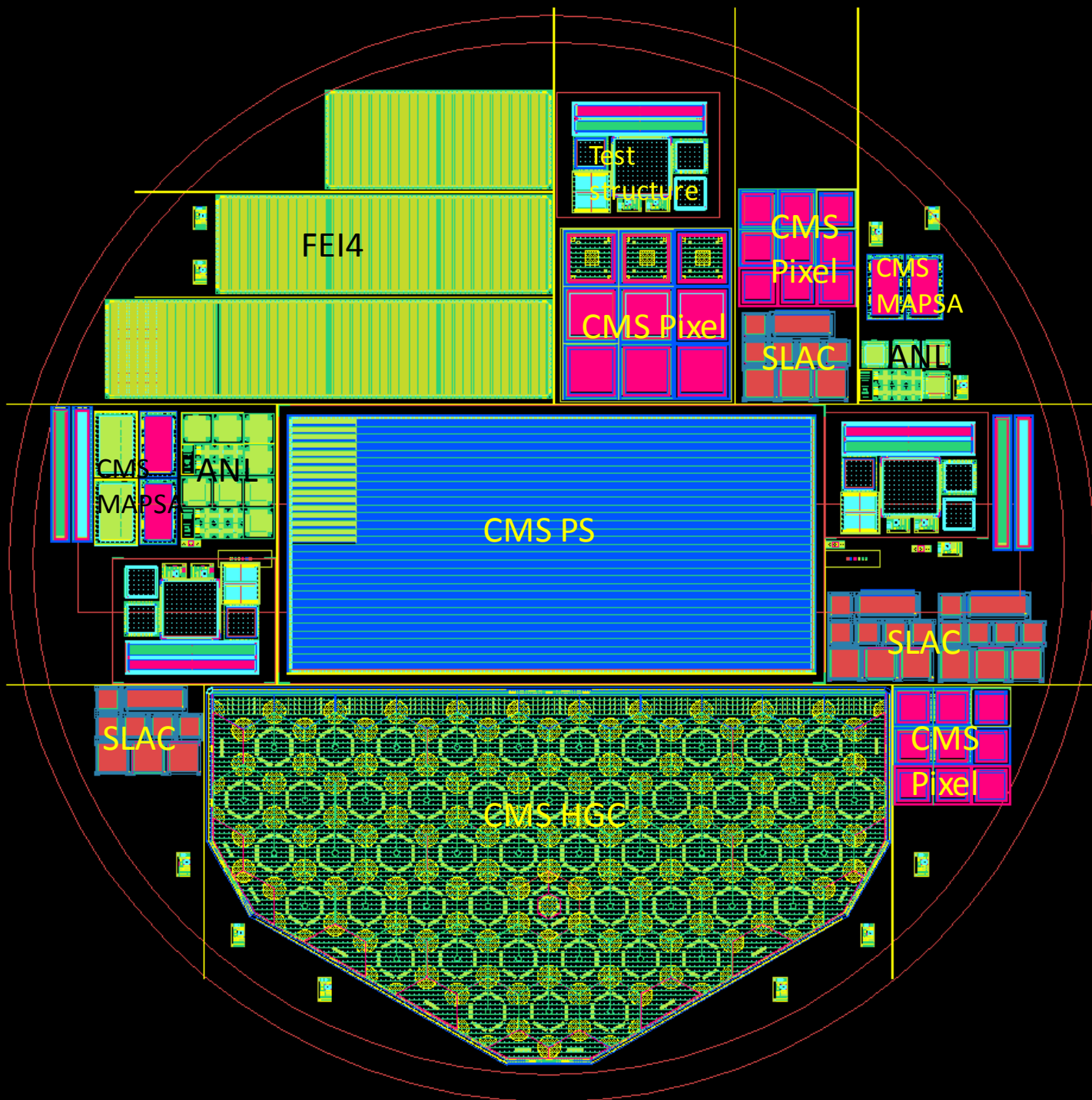
# Tezzaron/Novati SBIR Wafer

We expect to submit the designs in the next few days. This is necessary to meet the SBIR schedule

- We do not have the wafer material for direct bonded wafers (Si-Si) so we will use SOI wafers (Si-Oxide-Si)m which complicates backside processing but should be OK.
- We hope to fund a run with the same masks with the direct bonded wafers when they are received.
- Several new designs and variants of the guard rings



# Wafer layout



Guard  
Rings

SLAC

Original FNA

Argonne p-stop

Argonne no p-stop

HPK Style

CMS MPA

